

Yikai Wang

List of Publications by Year in descending order

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35
papers

926
citations

430442

18
h-index

454577

30
g-index

35
all docs

35
docs citations

35
times ranked

1277
citing authors

#	ARTICLE	IF	CITATIONS
1	Diffusion-Induced Stress in Commercial Graphite Electrodes during Multiple Cycles Measured by an In Situ Method. <i>Micromachines</i> , 2022, 13, 142.	1.4	7
2	Structure and mechanical properties of electroplated mossy lithium: Effects of current density and electrolyte. <i>Energy Storage Materials</i> , 2020, 26, 276-282.	9.5	11
3	Freeze-dried low-tortuous graphite electrodes with enhanced capacity utilization and rate capability. <i>Carbon</i> , 2020, 159, 133-139.	5.4	28
4	Real-time measurements of electro-mechanical coupled deformation and mechanical properties of commercial graphite electrodes. <i>Carbon</i> , 2020, 169, 258-263.	5.4	20
5	Lithium Substituted Poly(acrylic acid) as a Mechanically Robust Binder for Low-Cost Silicon Microparticle Electrodes. <i>ACS Applied Energy Materials</i> , 2020, 3, 10940-10949.	2.5	10
6	In-situ measurements of mechanical property and stress evolution of commercial graphite electrode. <i>Materials and Design</i> , 2020, 194, 108887.	3.3	19
7	Communicationâ€™ Controllable Deformation of Composite Graphite Electrodes during Electrochemical Process. <i>Journal of the Electrochemical Society</i> , 2020, 167, 140511.	1.3	1
8	Communicationâ€™ Fracture Behavior of Single $\text{LiNi}_{0.33}\text{Mn}_{0.33}\text{Co}_{0.33}\text{O}_2$ Particles Studied by Flat Punch Indentation. <i>Journal of the Electrochemical Society</i> , 2019, 166, A2749-A2751.	1.3	16
9	Mechanical behavior of electroplated mossy lithium at room temperature studied by flat punch indentation. <i>Applied Physics Letters</i> , 2019, 115, .	1.5	22
10	Effects of polymeric binders on the cracking behavior of silicon composite electrodes during electrochemical cycling. <i>Journal of Power Sources</i> , 2019, 438, 226938.	4.0	34
11	The Influence of Polyvinylidene Fluoride (PVDF) Binder Properties on $\text{LiNi}_{0.33}\text{Co}_{0.33}\text{Mn}_{0.33}\text{O}_2$ (NMC) Electrodes Made by a Dry-Powder-Coating Process. <i>Journal of the Electrochemical Society</i> , 2019, 166, A2151-A2157.	1.3	36
12	Spatial Molecular Layer Deposition of Ultrathin Polyamide To Stabilize Silicon Anodes in Lithium-Ion Batteries. <i>ACS Applied Energy Materials</i> , 2019, 2, 4135-4143.	2.5	20
13	Improving Ionic Conductivity with Bimodal-Sized $\text{Li}_7\text{La}_3\text{Zr}_2\text{O}_{12}$ Fillers for Composite Polymer Electrolytes. <i>ACS Applied Materials & Interfaces</i> , 2019, 11, 12467-12475.	4.0	100
14	Influence of polymeric binders on mechanical properties and microstructure evolution of silicon composite electrodes during electrochemical cycling. <i>Journal of Power Sources</i> , 2019, 425, 170-178.	4.0	46
15	Electrochemically induced fractures in crystalline silicon anodes. <i>Journal of Power Sources</i> , 2019, 425, 44-49.	4.0	14
16	Depth sensing indentation of magnesium/boron nitride nanocomposites. <i>Journal of Composite Materials</i> , 2019, 53, 1751-1763.	1.2	8
17	Indentation-based rate-dependent plastic deformation of polycrystalline pure magnesium. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2018, 716, 63-71.	2.6	24
18	Mechanical Property Evolution of Silicon Composite Electrodes Studied by Environmental Nanoindentation. <i>Advanced Energy Materials</i> , 2018, 8, 1702578.	10.2	51

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19	Role of polymeric binders on mechanical behavior and cracking resistance of silicon composite electrodes during electrochemical cycling. <i>Journal of Power Sources</i> , 2018, 387, 9-15.	4.0	55
20	Effects of cooling rate and magnetic field on solidification characteristics of Au ₈₀ Sn ₂₀ eutectic solder. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 436-445.	1.1	9
21	Linking lignin source with structural and electrochemical properties of lignin-derived carbon materials. <i>RSC Advances</i> , 2018, 8, 38721-38732.	1.7	42
22	Effects of adhesion and cohesion on the electrochemical performance and durability of silicon composite electrodes. <i>Journal of Power Sources</i> , 2018, 397, 223-230.	4.0	36
23	Unveiling the Critical Role of Polymeric Binders for Silicon Negative Electrodes in Lithium-Ion Full Cells. <i>ACS Applied Materials & Interfaces</i> , 2017, 9, 3562-3569.	4.0	55
24	A nanoindentation study of the viscoplastic behavior of pure lithium. <i>Scripta Materialia</i> , 2017, 130, 191-195.	2.6	60
25	Systematic Investigation of the Alucone-Coating Enhancement on Silicon Anodes. <i>ACS Applied Materials & Interfaces</i> , 2017, 9, 40143-40150.	4.0	18
26	In situ measurement of mechanical property and stress evolution in a composite silicon electrode. <i>Journal of Power Sources</i> , 2017, 366, 80-85.	4.0	51
27	Interfacial microstructure evolution and shear behavior of Au-12Ge/Ni solder joints during isothermal aging. <i>Journal of Materials Science: Materials in Electronics</i> , 2017, 28, 3685-3694.	1.1	9
28	Nanoindentation study on micromechanical behaviors of Au-Ni-Sn intermetallic layers in Au-20Sn/Ni solder joints. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2016, 653, 13-22.	2.6	16
29	Interfacial reaction mechanism and kinetics between Au-20Sn and Sn. <i>Journal of Materials Science: Materials in Electronics</i> , 2016, 27, 5982-5991.	1.1	5
30	Interfacial microstructure evolution and shear behavior of Au-20Sn/(Sn)Cu solder joints bonded at 250 °C. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2016, 651, 626-635.	2.6	30
31	Research progress of Ag ₃ PO ₄ -based photocatalyst: Fundamentals and performance enhancement. <i>Transactions of Nonferrous Metals Society of China</i> , 2015, 25, 112-121.	1.7	24
32	Formation and evolution of intermetallic compounds between the In-3Ag solder and Cu substrate during soldering. <i>Journal of Materials Science: Materials in Electronics</i> , 2015, 26, 7967-7976.	1.1	1
33	Indentation size effect of stress exponent and hardness in homogeneous duplex eutectic 80Au/20Sn. <i>Materials Letters</i> , 2014, 120, 151-154.	1.3	11
34	Indentation size effect and micromechanics characterization of intermetallic compounds in the Au-Sn system. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2014, 610, 161-170.	2.6	23
35	Indentation depth dependent micromechanical properties and rate dependent pop-in events of (Au,Cu) ₅ Sn. <i>Materials Letters</i> , 2014, 131, 57-60.	1.3	14